



# PNE20060CPE-Q

200 V, 2 x 3 A dual common cathode hyperfast recovery rectifier

10 September 2021

Product data sheet

## 1. General description

High power density, hyperfast switching time dual recovery rectifier in common cathode configuration with high-efficiency planar technology, encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Reverse voltage:  $V_R \leq 200$  V
- Forward current:  $I_F \leq 3$  A (per diode)
- Switching time:  $t_{tr} \leq 30$  ns
- Pt doped life time control
- Low inductance
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- High power capability due to clip-bond technology
- Planar die design
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- General-purpose rectification
- Hyperfast switching
- Solenoid control
- Piezo injection
- Freewheeling applications

## 4. Quick reference data

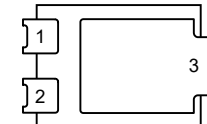
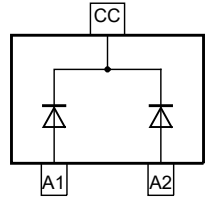
Table 1. Quick reference data

| Symbol  | Parameter                       | Conditions   |     | Min | Typ | Max | Unit    |
|---|---------------------------------|--|-----|-----|-----|-----|---------|
| <b>Per diode (unless otherwise specified)</b> |                                 |  |     |     |     |     |         |
| $I_{F(AV)}$                                   | average forward current         | $\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 155$ °C |     | -   | -   | 3   | A       |
| $V_{RRM}$                                     | repetitive peak reverse voltage | $T_j = 25$ °C  |     | -   | -   | 200 | V       |
| $V_R$   | reverse voltage                 |  |     | -   | -   | 200 | V       |
| $V_F$   | forward voltage                 | $I_F = 3$ A; $T_j = 25$ °C                                       | [1] | -   | 870 | 940 | mV      |
|   |                                 | $I_F = 3$ A; $T_j = 125$ °C                                      | [1] | -   | 730 | 820 | mV      |
| $I_R$   | reverse current                 | $V_R = 200$ V; $T_j = 25$ °C                                     | [1] | -   | -   | 1   | $\mu$ A |
|   |                                 | $V_R = 200$ V; $T_j = 125$ °C                                    | [1] | -   | 1.5 | 35  | $\mu$ A |

[1] Very short pulse, in order to maintain a stable junction temperature.

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description     | Simplified outline   | Graphic symbol  |
|-----|--------|-----------------|--|---|
| 1   | A1     | anode (diode 1) |  <p>CFP15B (SOT1289B)</p> |  <p>aaa-030081</p> |
| 2   | A2     | anode (diode 2) |  |   |
| 3   | CC     | common cathode  |  |   |

## 6. Ordering information

Table 3. Ordering information

| Type number   | Package |  |          |
|---------------|---------|--|----------|
|               | Name    | Description  | Version  |
| PNE20060CPE-Q | CFP15B  | plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body | SOT1289B |

## 7. Marking

Table 4. Marking codes

| Type number   | Marking code |
|---------------|--------------|
| PNE20060CPE-Q | 200E<br>006C |

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC60134)

| Symbol  | Parameter                           | Conditions   |     | Min | Max  | Unit |
|---|-------------------------------------|--|-----|-----|------|------|
| <b>Per diode (unless otherwise specified)</b> |                                     |  |     |     |      |      |
| $V_R$   | reverse voltage                     | $T_j = 25\text{ °C}$   |     | -   | 200  | V    |
| $V_{RRM}$                                     | repetitive peak reverse voltage     |  |     | -   | 200  | V    |
| $V_{R(RMS)lim}$                               | limiting RMS reverse voltage        |  |     | -   | 140  | V    |
| $I_F$   | forward current                     | $\delta = 1; T_{sp} \leq 150\text{ °C}$  |     | -   | 4.2  | A    |
| $I_{F(AV)}$                                   | average forward current             | $\delta = 0.5; f = 20\text{ kHz};$ square wave; $T_{sp} \leq 155\text{ °C}$  |     | -   | 3    | A    |
| $I_{FSM}$                                     | non-repetitive peak forward current | $t_p = 8.3\text{ ms};$ single half sine wave (applied at rated load condition); $T_{j(init)} = 25\text{ °C}$             |     | -   | 80   | A    |
|   |                                     | $t_p = 8.3\text{ ms};$ single half sine wave (applied at rated load condition); per device; $T_{j(init)} = 25\text{ °C}$ |     | -   | 150  | A    |
| <b>Per device, one diode loaded</b>           |                                     |  |     |     |      |      |
| $P_{tot}$                                     | total power dissipation             | $T_{amb} \leq 25\text{ °C}$  | [1] | -   | 1.66 | W    |
|   |                                     |  | [2] | -   | 2.15 | W    |
| $T_j$   | junction temperature                |  |     | -   | 175  | °C   |
| $T_{amb}$                                     | ambient temperature                 |  |     | -55 | 175  | °C   |
| $T_{stg}$                                     | storage temperature                 |  |     | -65 | 175  | °C   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

### 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol                              | Parameter  | Conditions  | Min | Typ | Max | Unit |     |
|-------------------------------------|--|-------------|-----|-----|-----|------|-----|
| <b>Per device, one diode loaded</b> |  |             |     |     |     |      |     |
| $R_{th(j-a)}$                       | thermal resistance from junction to ambient      | in free air | [1] | -   | -   | 90   | K/W |
|                                     |  |             | [2] | -   | -   | 70   | K/W |
| $R_{th(j-sp)}$                      | thermal resistance from junction to solder point |             | [3] | -   | -   | 7    | K/W |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [3] Soldering point of cathode tab.

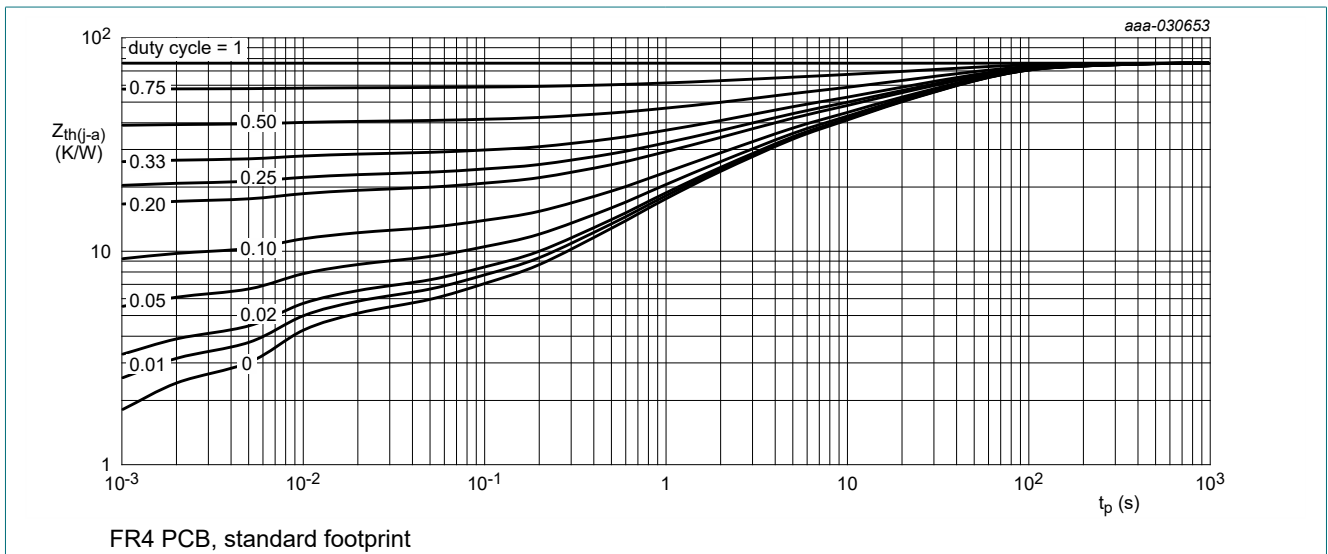


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

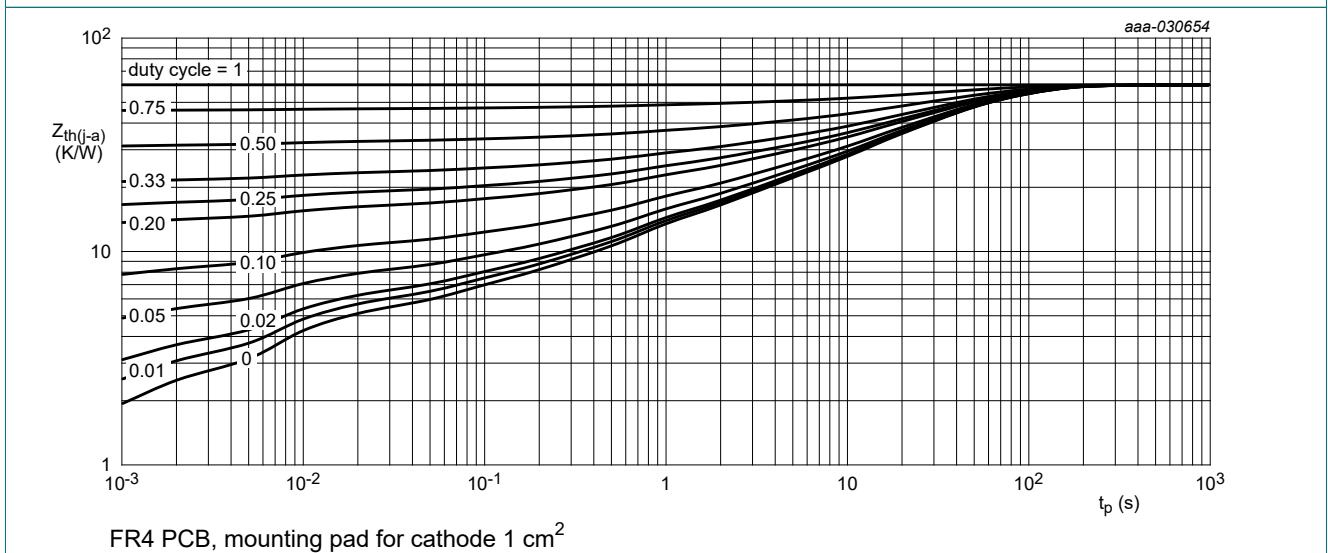


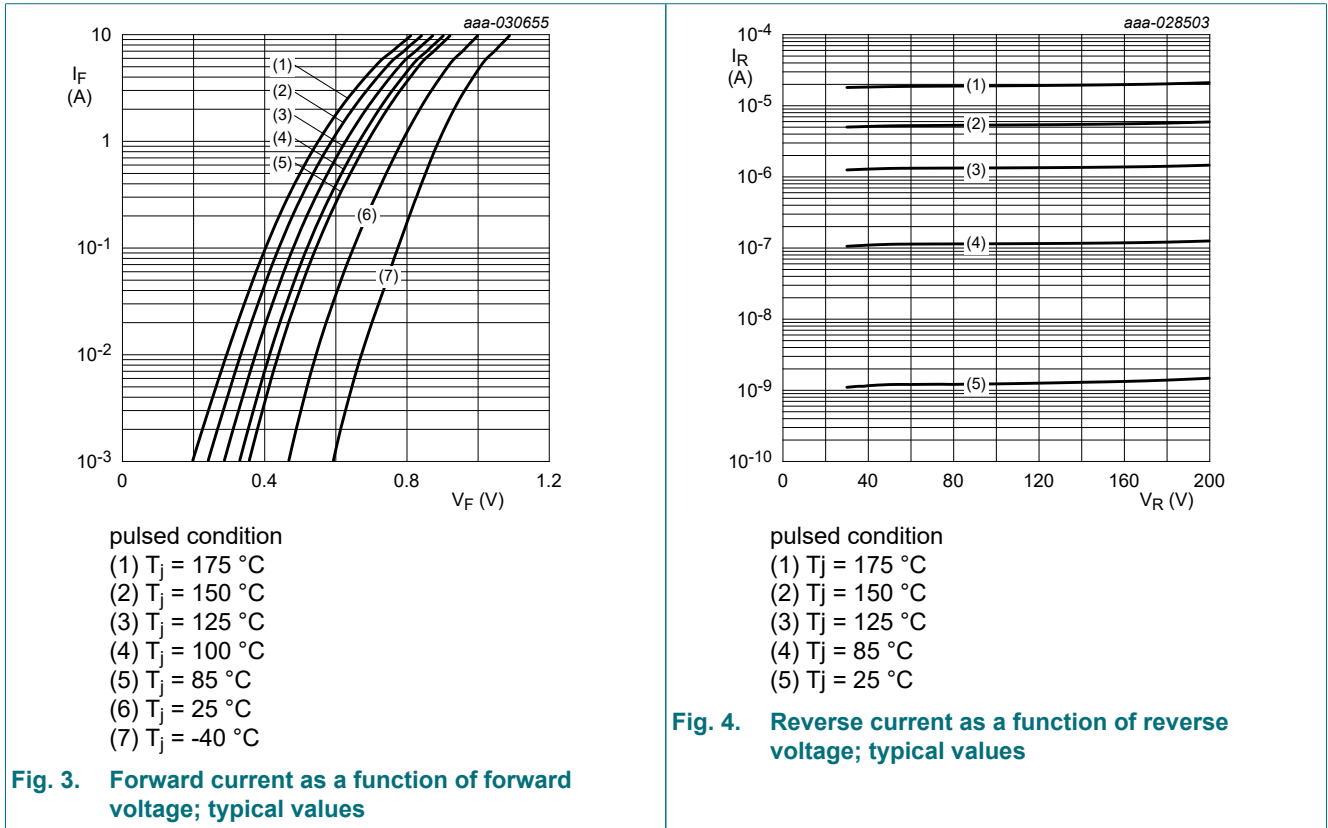
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

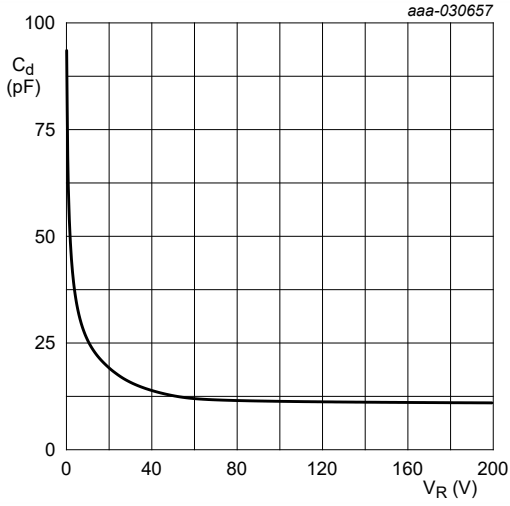
### 10. Characteristics

Table 7. Characteristics

| Symbol  | Parameter                           | Conditions  | Min | Typ | Max | Unit |         |
|---|-------------------------------------|---|-----|-----|-----|------|---------|
| <b>Per diode (unless otherwise specified)</b> |                                     |   |     |     |     |      |         |
| $V_{(BR)R}$                                   | reverse breakdown voltage           | $I_R = 100 \mu A; T_j = 25 \text{ }^\circ C$                              | [1] | 200 | -   | V    |         |
| $V_F$   | forward voltage                     | $I_F = 3 A; T_j = 25 \text{ }^\circ C$                                    | [1] | -   | 870 | 940  | mV      |
|   |                                     | $I_F = 3 A; T_j = 125 \text{ }^\circ C$                                   | [1] | -   | 730 | 820  | mV      |
| $I_R$   | reverse current                     | $V_R = 200 V; T_j = 25 \text{ }^\circ C$                                  | [1] | -   | -   | 1    | $\mu A$ |
|   |                                     | $V_R = 200 V; T_j = 125 \text{ }^\circ C$                                 | [1] | -   | 1.5 | 35   | $\mu A$ |
| $C_d$   | diode capacitance                   | $V_R = 4 V; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$                 | -   | 37  | -   | pF   |         |
| $t_{rr}$                                      | reverse recovery time step recovery | $I_F = 0.5 A; I_R = 1 A; I_{R(meas)} = 0.25 A; T_j = 25 \text{ }^\circ C$ | -   | 13  | 30  | ns   |         |
|   | reverse recovery time ramp recovery | $di_F/dt = 50 A/\mu s; I_F = 1 A; V_R = 30 V; T_j = 25 \text{ }^\circ C$  | -   | 22  | -   | ns   |         |
|   | reverse recovery time               | $di_F/dt = 100 A/\mu s; I_F = 1 A; V_R = 30 V; T_j = 25 \text{ }^\circ C$ | -   | 17  | -   | ns   |         |
| $I_{RM}$                                      | peak reverse recovery current       | $T_j = 25 \text{ }^\circ C$   | -   | 1   | -   | A    |         |
| $Q_{rr}$                                      | reverse recovery charge             |   | -   | 10  | -   | nC   |         |
| $V_{FRM}$                                     | peak forward recovery voltage       | $I_F = 1 A; di_F/dt = 50 A/\mu s; T_j = 25 \text{ }^\circ C$              | -   | 815 | -   | mV   |         |

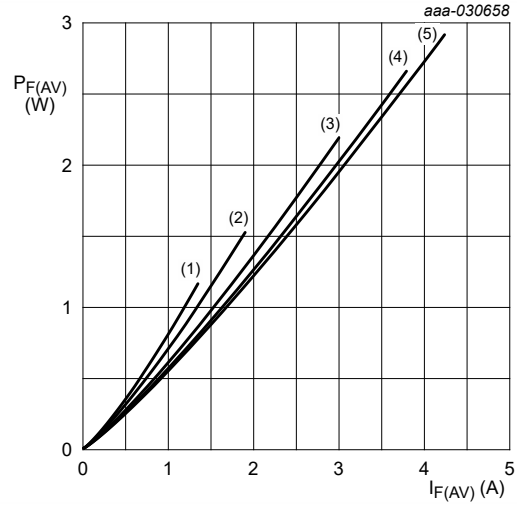
[1] Very short pulse, in order to maintain a stable junction temperature.





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

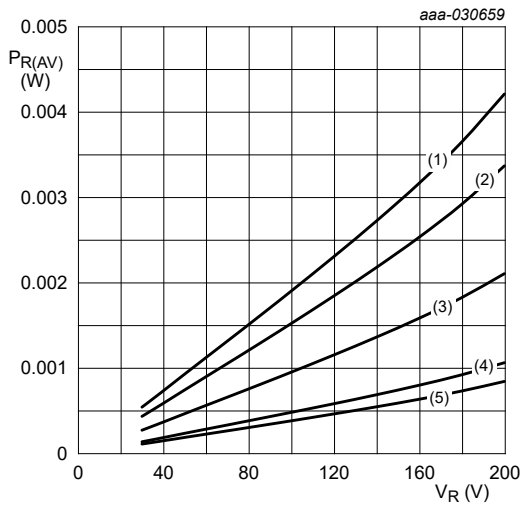
**Fig. 5. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 175 \text{ }^\circ\text{C}$

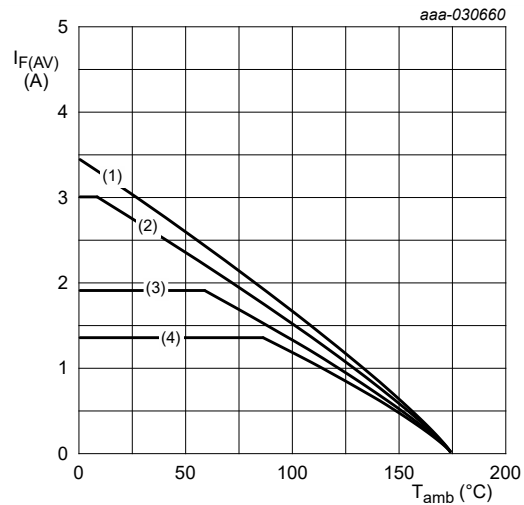
- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 0.8$
- (5)  $\delta = 1; \text{DC}$

**Fig. 6. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 175 \text{ }^\circ\text{C}$   
 (1)  $\delta = 1; \text{DC}$   
 (2)  $\delta = 0.9$   
 (3)  $\delta = 0.8$   
 (4)  $\delta = 0.5$   
 (5)  $\delta = 0.2$

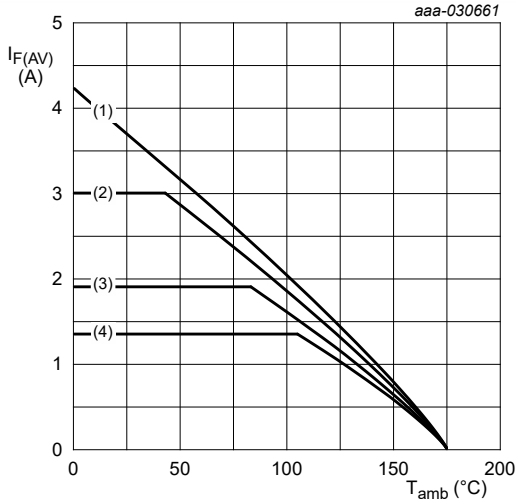
**Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values**



FR4 PCB, standard footprint  
 $T_j = 175 \text{ }^\circ\text{C}$   
 (1)  $\delta = 1; \text{DC}$   
 (2)  $\delta = 0.5; f = 20 \text{ kHz}$   
 (3)  $\delta = 0.2; f = 20 \text{ kHz}$   
 (4)  $\delta = 0.1; f = 20 \text{ kHz}$

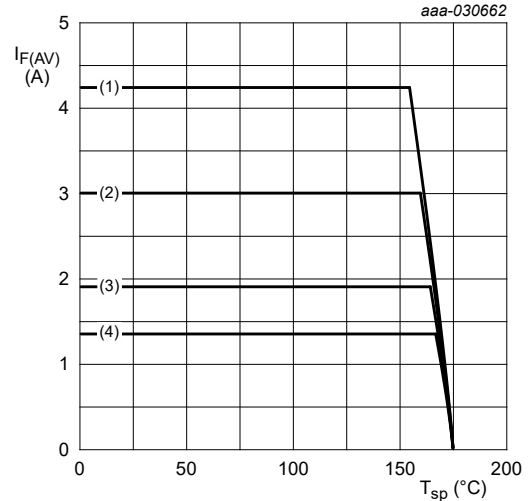
**Fig. 8. Average forward current as a function of ambient temperature; typical values**

200 V, 2 x 3 A dual common cathode hyperfast recovery rectifier



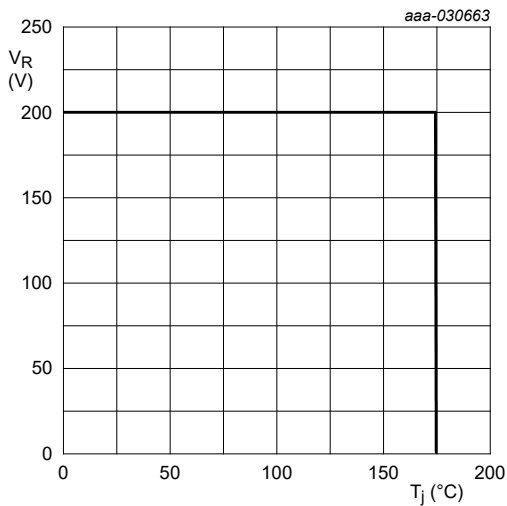
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 175$  °C  
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20$  kHz  
 (3)  $\delta = 0.2$ ;  $f = 20$  kHz  
 (4)  $\delta = 0.1$ ;  $f = 20$  kHz

**Fig. 9. Average forward current as a function of ambient temperature; typical values**



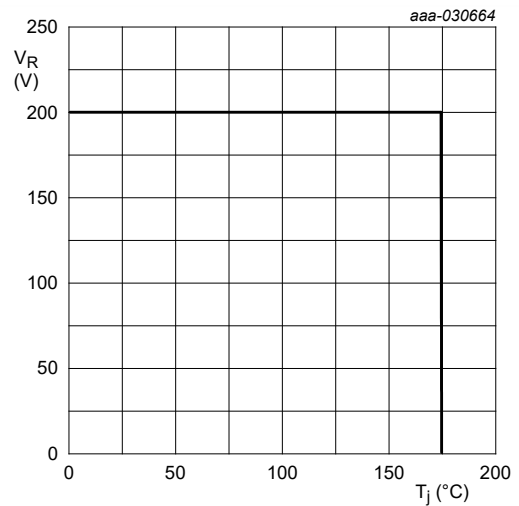
$T_j = 175$  °C  
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20$  kHz  
 (3)  $\delta = 0.2$ ;  $f = 20$  kHz  
 (4)  $\delta = 0.1$ ;  $f = 20$  kHz

**Fig. 10. Average forward current as a function of solder point temperature; typical values**



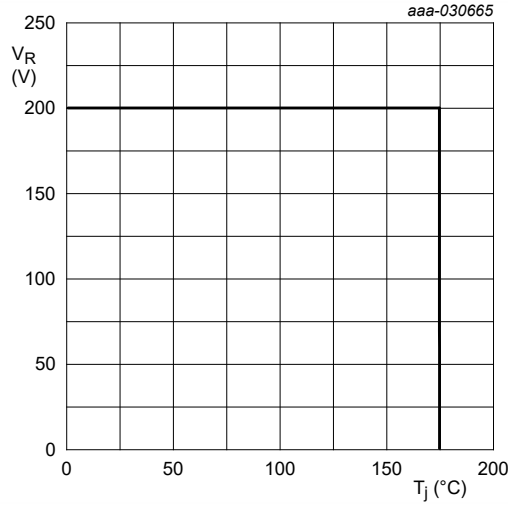
FR4 PCB, standard footprint  
 $R_{th} = 90$  K/W

**Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values**



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $R_{th} = 70$  K/W

**Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values**



Soldering point of cathode tab  
 $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

### 11. Test information

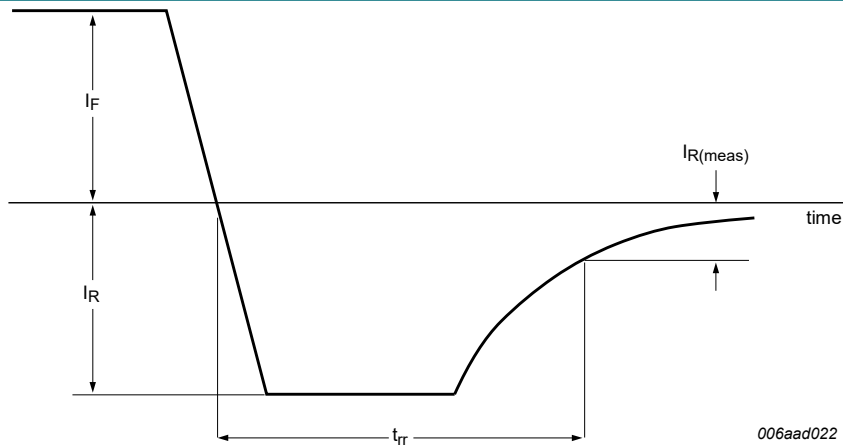


Fig. 14. Reverse recovery definition; step recovery

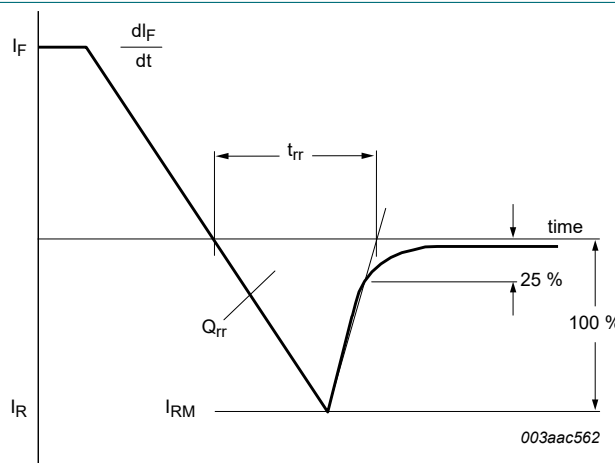


Fig. 15. Reverse recovery definition; ramp recovery



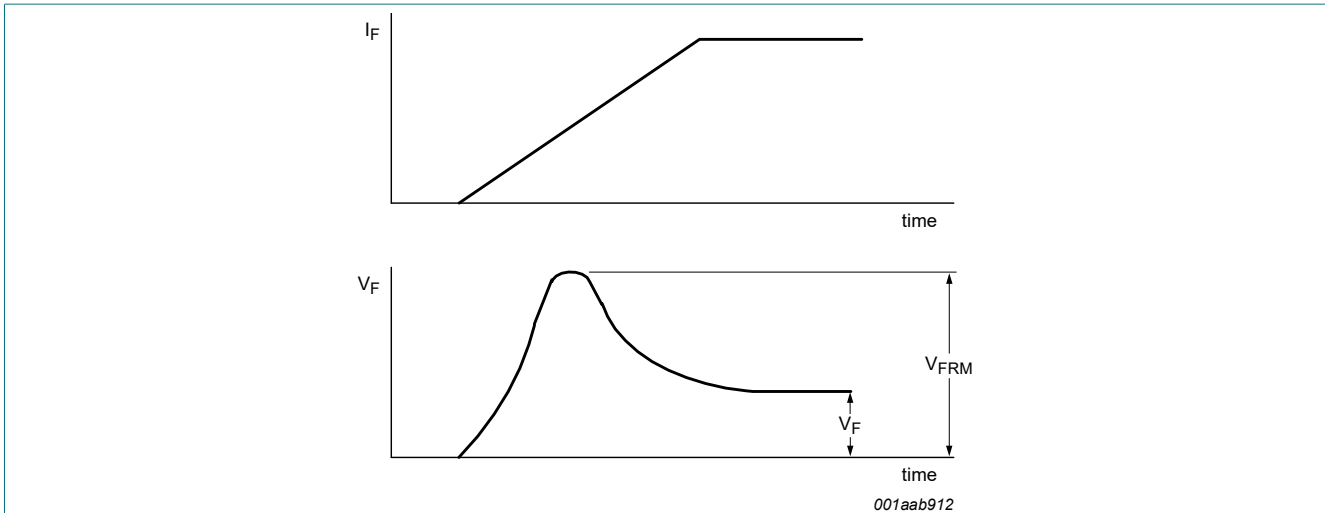


Fig. 16. Forward recovery definition

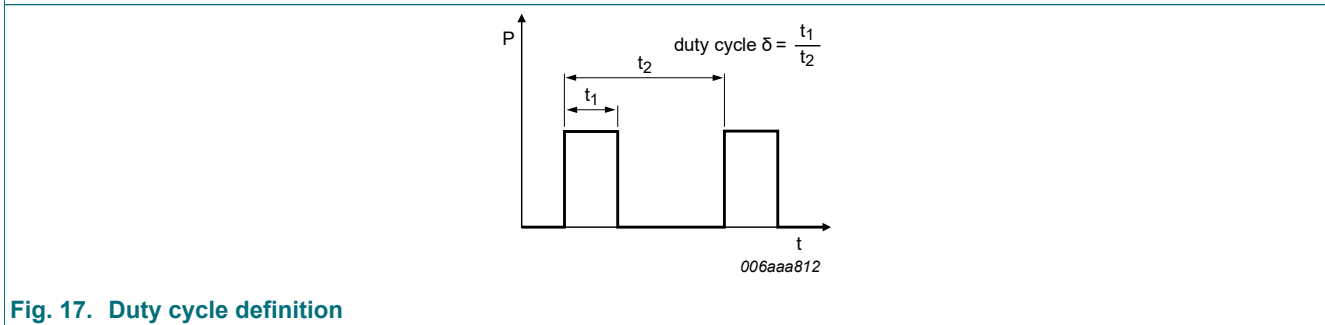


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with  $I_{RMS}$  defined as RMS current.

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline

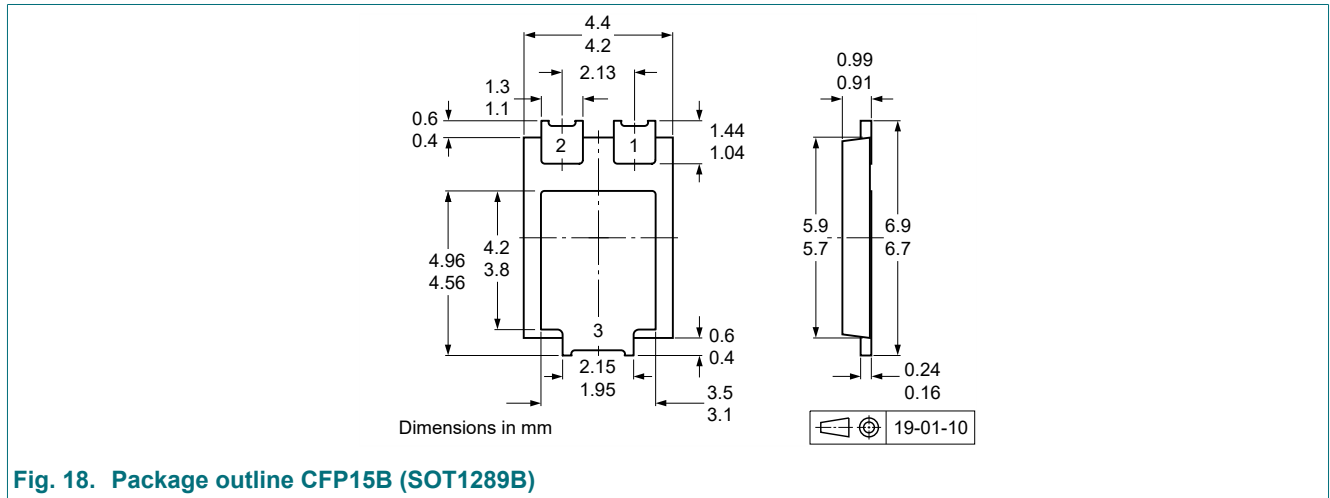


Fig. 18. Package outline CFP15B (SOT1289B)

## 13. Soldering

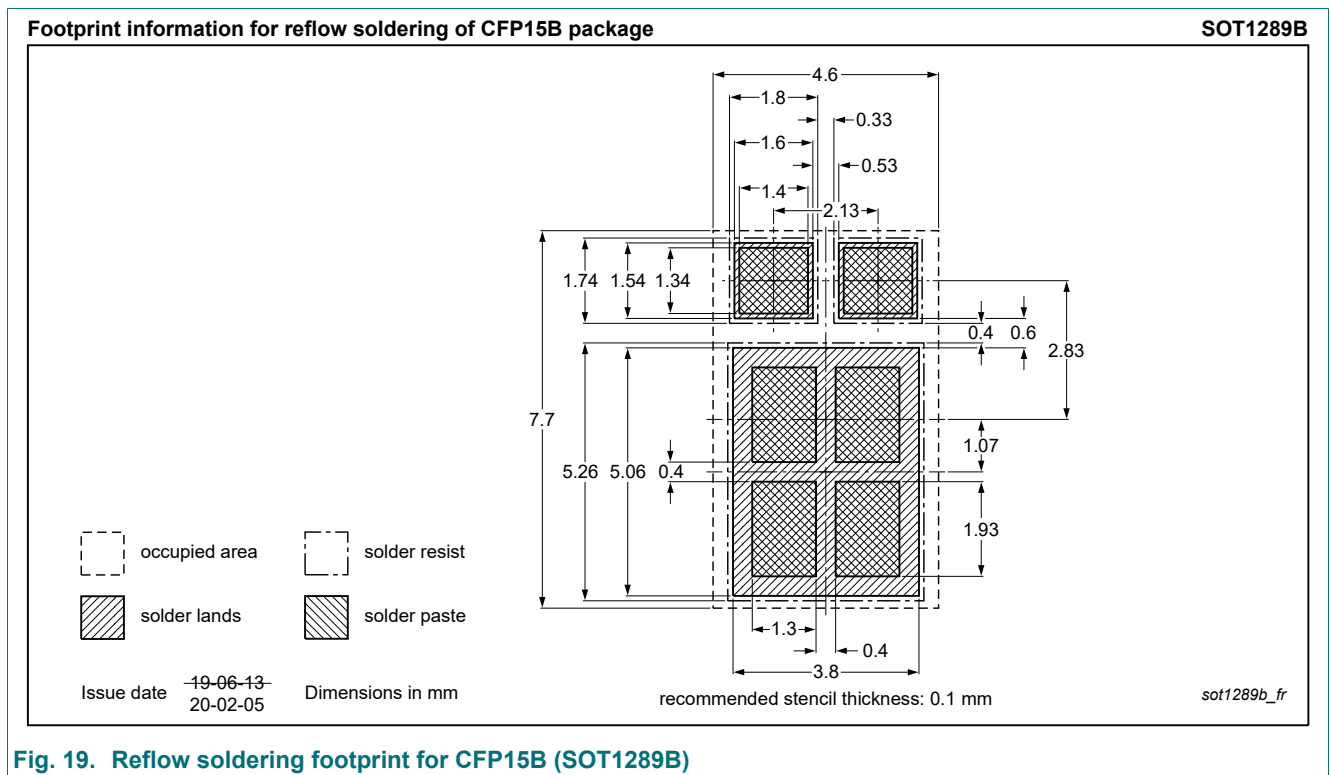


Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)

## 14. Revision history

Table 8. Revision history

| Data sheet ID     | Release date | Data sheet status  | Change notice | Supersedes |
|-------------------|--------------|--------------------|---------------|------------|
| PNE20060CPE-Q v.1 | 20210910     | Product data sheet | -             | -          |

## 15. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 10 September 2021

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